



Semiconductor Device Type: ACZL (7BX) 008 MSOP 3x3x1.0mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e4		
Basic Substance	CAS Number	'Contained In' Sub-Component	% Total Weight	mg/part	ppm	(mg) Total	Mold Compound	% of Total Weight			
Silica, vitreous	60676-86-0	Mold Compound	38.318	9.426	383,180	11.09	Silica, vitreous	60676-86-0	85.00	45.08	
Epoxy Resin	Trade Secret	Mold Compound	6.672	1.641	66,718		Epoxy Resin	Trade Secret	14.80		
Carbon black	1333-86-4	Mold Compound	0.090	0.022	902		Carbon black	1333-86-4	0.20		
Total						100.00					
Copper	7440-50-8	Lead Frame	44.464	10.938	444,643	11.27	(mg) Total		Lead Frame	% of Total Weight	45.83
Iron	7439-89-6	Lead Frame	1.123	0.276	11,228		Copper	7440-50-8	97.02		
Zinc	7440-66-6	Lead Frame	0.160	0.039	1,604		Iron	7439-89-6	2.45		
Phosphorous	7723-14-0	Lead Frame	0.082	0.020	825	Silver	7440-22-4	5.850			
Silver	7440-22-4	Die Attach	0.585	0.144	5,850	Die Attach	7440-66-6	0.35			
Diester Resin	94-80-4	Die Attach	0.117	0.029	1,170	Diester Resin	94-80-4	15.00			
Functionalized Urethane Resin	72869-86-4	Die Attach	0.039	0.010	390	Functionalized Urethane Resin	72869-86-4	5.00			
Epoxy Resin	9003-36-5	Die Attach	0.020	0.005	195	Epoxy Resin	9003-36-5	2.50			
Epoxy Resin	13561-08-5	Die Attach	0.020	0.005	195	Epoxy Resin	13561-08-5	2.50			
Silicon	7440-21-3	Chip (Die)	5.640	1.387	56,400	Total			100.00		
Gold	7440-57-5	Wire Bond	1.930	0.475	19,300	0.19	(mg) Total		Die Attach	% of Total Weight	0.78
Nickel	7440-02-0	Plating on external leads (pins)	0.666	0.164	6,660	Silver	7440-22-4	75.00			
Palladium	7440-05-3	Plating on external leads (pins)	0.037	0.009	370	Diester Resin	94-80-4	15.00			
Gold	7440-57-5	Plating on external leads (pins)	0.037	0.009	370	Functionalized Urethane Resin	72869-86-4	5.00			
TOTALS:						100.000	24.600	1,000,000			
0.0246 g Total Mass											
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)											
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.											
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.											
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/											
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.											
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table											
						1.39	Total (mg)		Chip (Die)	% of Total Weight	5.64
							Doped Silicon	7440-21-3	100		
						Total			100.00		
						0.47	(mg) Total		Wire Bond	% of Total Weight	1.93
							Gold	7440-57-5	100.00		
						Total			100.00		
						0.18	(mg) Total		Plating on external leads (pins)	% of Total Weight	0.74
							Nickel	7440-02-0	90.00		
							Palladium	7440-05-3	5.00		
							Gold	7440-57-5	5.00		
						Total			100.00		

24.60

100.00